

MC10138

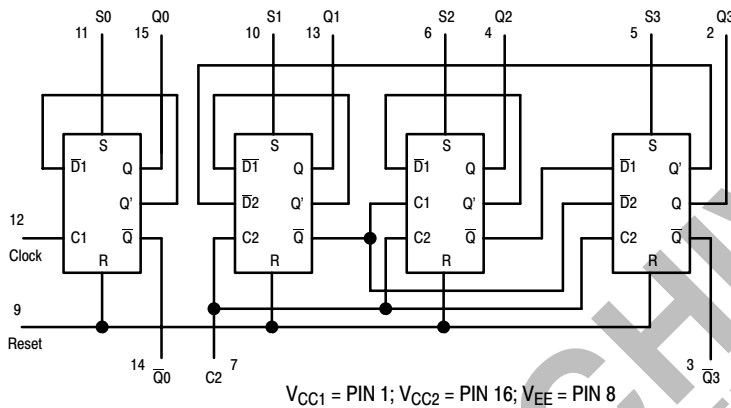
Bi-Quinary Counter

The MC10138 is a four bit counter capable of divide by two, five, or ten functions. It is composed of four set–reset master–slave flip–flops. Clock inputs trigger on the positive going edge of the clock pulse.

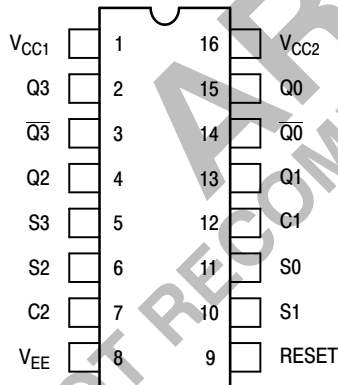
Set or reset input override the clock, allowing asynchronous “set” or “clear.” Individual set and common reset inputs are provided, as well as complementary outputs for the first and fourth bits.

- $P_D = 370 \text{ mW typ/pkg (No Load)}$
- $f_{\text{tog}} = 150 \text{ MHz typ}$
- $t_r, t_f = 2.5 \text{ ns typ (20\%–80\%)}$

LOGIC DIAGRAM



DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package.

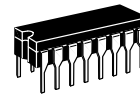
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



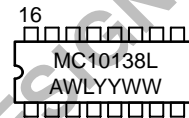
ON Semiconductor

<http://onsemi.com>

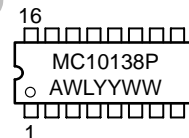
MARKING DIAGRAMS



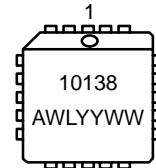
CDIP-16
L SUFFIX
CASE 620



PDIP-16
P SUFFIX
CASE 648



PLCC-20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10138L	CDIP-16	25 Units / Rail
MC10138P	PDIP-16	25 Units / Rail
MC10138FN	PLCC-20	46 Units / Rail

MC10138

COUNTER TRUTH TABLES

BI-QUINARY

(Clock connected to C2
and $\overline{Q3}$ connected to C1)

COUNT	Q1	Q2	Q3	Q0
0	L	L	L	L
1	H	L	L	L
2	L	H	L	L
3	H	H	L	L
4	L	L	H	L
5	L	L	L	H
6	H	L	L	H
7	L	H	L	H
8	H	H	L	H
9	L	L	H	H

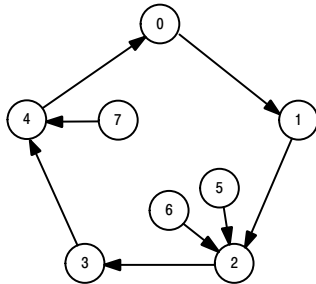
BCD

(Clock connected to C1
and $\overline{Q0}$ connected to C2)

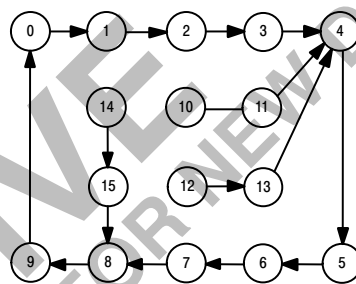
COUNT	Q0	Q1	Q2	Q3
0	L	L	L	L
1	H	L	L	L
2	L	H	L	L
3	H	H	L	L
4	L	L	H	L
5	H	L	H	L
6	L	H	H	L
7	H	H	H	L
8	L	L	L	H
9	H	L	L	H

COUNTER STATE DIAGRAM — POSITIVE LOGIC

CLOCK CONNECTED TO C2



$\overline{Q0}$ CONNECTED TO C2



ARCHIVE FOR NEW DESIGN


DEVICE NOT RECOMMENDED


MC10138

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Pin Under Test	Test Limits						Unit			
			-30°C		+25°C		+85°C					
			Min	Max	Min	Typ	Max	Min		Max		
Power Supply Drain Current	I_E	8		97		70	88		97	mAdc		
Input Current	I_{inH}	12		350			220		220	μ Adc		
		5,6,10,11		390			245		245			
		7		460			290		290			
		9		650			410					
	I_{inL}	All	0.5		0.5			0.3		μ Adc		
Output Voltage Logic 1	V_{OH}	3,14 (3.)	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdc		
		2,4,13,15 (2.)	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700			
Output Voltage Logic 0	V_{OL}	3,14 (2.)	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdc		
		2,4,13,15 (3.)	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615			
Threshold Voltage Logic 1	V_{OHA}	2,4,13,15 (2.)	-1.080		-0.980			-0.910		Vdc		
		3,14 (3.)	-1.080		-0.980			-0.910				
		13,15 (2.)	-1.080		-0.980			-0.910				
Threshold Voltage Logic 0	V_{OLA}	2,4,13,15 (3.)		-1.655			-1.630		-1.595	Vdc		
		3,14 (2.)		-1.655			-1.630		-1.595			
		13,15 (3.)		-1.655			-1.630		-1.595			
Switching Times (50 Ω Load)										ns		
Propagation Clock Delays Delay	t_{12+15+}	15	1.4	5.0	1.5	3.5	4.8	1.5	5.3			
		14	1.4	5.0	1.5	3.5	4.8	1.5	5.3			
		13	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		4	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		2	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		3	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		15	1.4	5.0	1.5	3.5	4.8	1.5	5.3			
		14	1.4	5.0	1.5	3.5	4.8	1.5	5.3			
		13	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		4	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		2	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		3	1.4	5.2	1.5	3.5	5.0	1.5	5.5			
		Set Delay	t_{11+15+}	15	1.4	5.2	1.5		5.0		1.5	5.5
				14	1.4	5.2	1.5		5.0		1.5	5.5
Reset Delay	t_{9+14+}	14	1.4	5.2	1.5		5.0	1.5	5.5			
		15	1.4	5.2	1.5		5.0	1.5	5.5			
Rise Time (20 to 80%)	t_{14+}	14	1.1	4.7	1.1	2.5	4.5	1.1	5.0			
		15	1.1	4.7	1.1	2.5	4.5	1.1	5.0			
Fall Time (20 to 80%)	t_{14-}	14	1.1	4.7	1.1	2.5	4.5	1.1	5.0			
		15	1.1	4.7	1.1	2.5	4.5	1.1	5.0			
Counting Frequency	f_{count}	2	125		125	150		125		MHz		
		15	125		125	150		125				

1. Individually test each input; apply V_{ILmin} to pin under test.

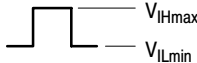
2. Set all four flip-flops by applying pulse  to pins 5, 6, 10, and 11 prior to applying test voltage indicated.

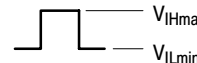
3. Reset all four flip-flops by applying pulse  to pin 9 prior to applying test voltage indicated.

ELECTRICAL CHARACTERISTICS (continued)

Characteristic	Symbol	Pin Under Test	TEST VOLTAGE VALUES (Volts)					(V _{CC}) Gnd			
			@ Test Temperature								
			V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmx}	V _{EE}				
NOTE: Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.			-30°C	-0.890	-1.890	-1.205	-1.500	-5.2			
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2			
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2			
			TEST VOLTAGE APPLIED TO PINS LISTED BELOW								
			V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmx}	V _{EE}				
Power Supply Drain Current	I _E	8	9				8	1, 16			
Input Current	I _{inH}	12	12				8	1, 16			
		5,6,10,11	5,6,10,11				8	1, 16			
		7	7				8	1, 16			
		9	9				8	1, 16			
	I _{inL}	All		Note 1.			8	1, 16			
Output Voltage Logic 1	V _{OH}	3,14 (3.)	9				8	1, 16			
		2,4,13,15 (2.)	5,6,10,11				8	1, 16			
Output Voltage Logic 0	V _{OL}	3,14 (2.)	5,6,10,11				8	1, 16			
		2,4,13,15 (3.)	9				8	1, 16			
Threshold Voltage Logic 1	V _{OHA}	2,4,13,15 (2.)			5,6,10,11		8	1, 16			
		3,14 (3.)			9		8	1, 16			
		13,15 (2.)			7,12		8	1, 16			
Threshold Voltage Logic 0	V _{OLA}	2,4,13,15 (3.)				5,6,10,11	8	1, 16			
		3,14 (2.)				9	8	1, 16			
		13,15 (3.)				7,12	8	1, 16			
Switching Times (50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V			
Propagation Delay Clock Delays	t ₁₂₊₁₅₊ t ₁₂₊₁₄₊ t ₇₊₁₃₊ t ₇₊₄₊ t ₇₊₂₊ t ₇₊₃₊ t ₁₂₊₁₅₋ t ₁₂₊₁₄₋ t ₇₊₁₃₋ t ₇₊₄₋ t ₇₊₂₋ t ₇₊₃₋	15				12	15	8	1, 16		
		14				12	14	8	1, 16		
		13				7	13	8	1, 16		
		4				7	4	8	1, 16		
		2				7	2	8	1, 16		
		3				7	3	8	1, 16		
		15				12	15	8	1, 16		
		14				12	14	8	1, 16		
		13				7	13	8	1, 16		
		4				7	4	8	1, 16		
		2				7	2	8	1, 16		
		3				7	3	8	1, 16		
		Set Delay	t ₁₁₊₁₅₊ t ₁₁₊₁₄₋	15				11	15	8	1, 16
				14				11	14	8	1, 16
Reset Delay	t ₉₊₁₄₊ t ₉₊₁₅₋	14				9	14	8	1, 16		
		15				9	15	8	1, 16		
Rise Time (20 to 80%)	t ₁₄₊ t ₁₅₊	14				11	14	8	1, 16		
		15				11	15	8	1, 16		
Fall Time (20 to 80%)	t ₁₄₋ t ₁₅₋	14				9	14	8	1, 16		
		15				9	15	8	1, 16		
Counting Frequency	f _{count}	2				7	2	8	1, 16		
		15				12	15	8	1, 16		

1. Individually test each input; apply V_{ILmin} to pin under test.

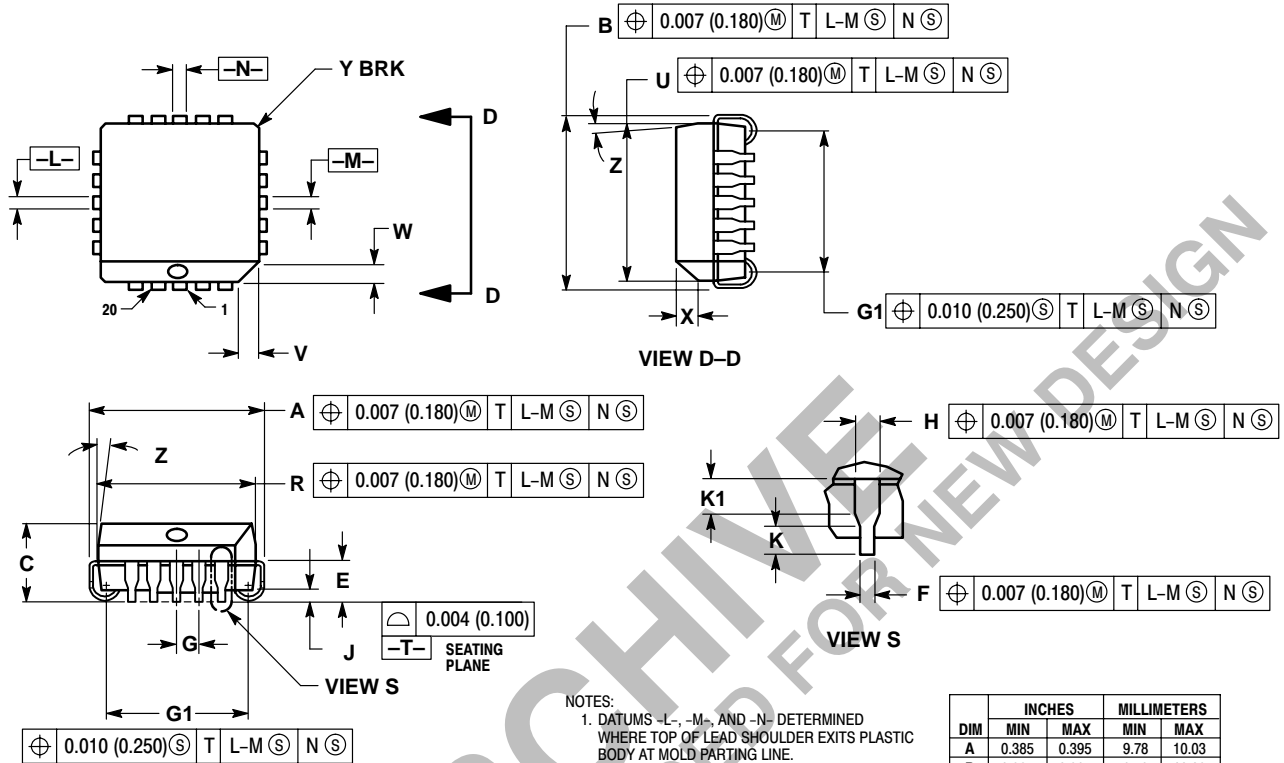
2. Set all four flip-flops by applying pulse  to pins 5, 6, 10, and 11 prior to applying test voltage indicated.

3. Reset all four flip-flops by applying pulse  to pin 9 prior to applying test voltage indicated.

MC10138

PACKAGE DIMENSIONS

PLCC-20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775-02
ISSUE C



NOTES:

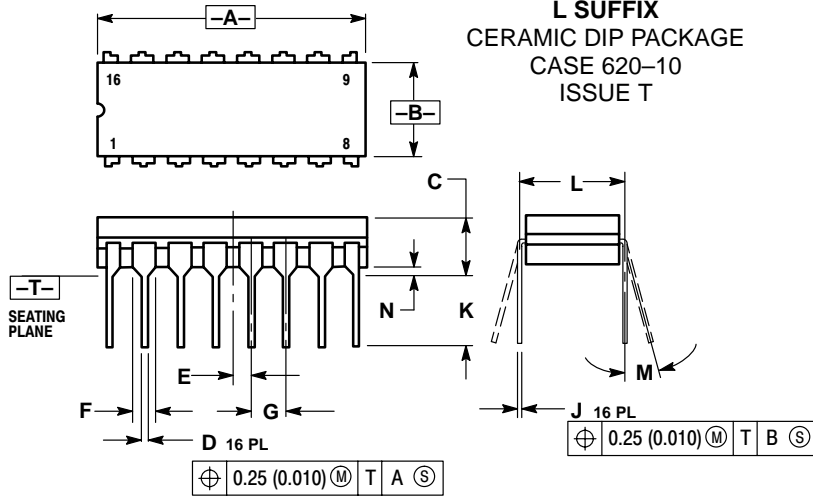
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

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PACKAGE DIMENSIONS

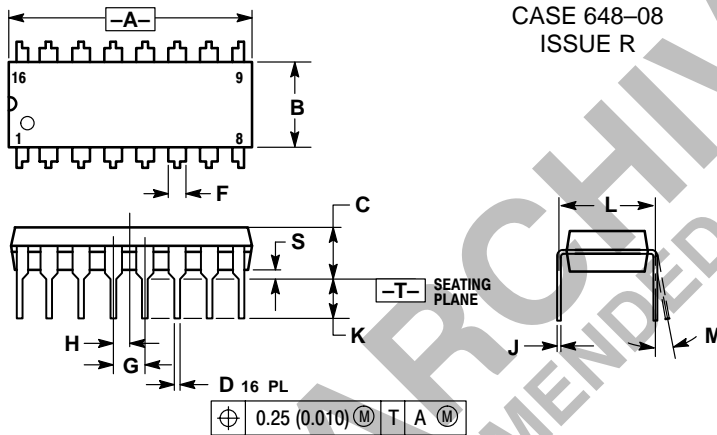
CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE T



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R




- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

Notes

ARCHIVE
DEVICE NOT RECOMMENDED FOR NEW DESIGN

ARCHIVE
RECOMMENDED FOR NEW DESIGN

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